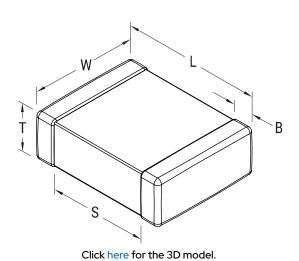




SMD Comm X8G HT150C Flex, Ceramic, 0.039 uF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	52 mg
Shelf Life	78 Weeks
MSL	1

1210
3.3mm +/-0.4mm
2.6mm +/-0.3mm
1.55mm +/-0.20mm
1.5mm MIN
0.6mm +/-0.25mm
2

8000

Packaging Quantity

W	2.6mm +/-0.3mm	Tolerance	
Т	1.55mm +/-0.20mm	Voltage DC	
S	1.5mm MIN	Dielectric Withstanding Voltage	
В	0.6mm +/-0.25mm	Temperature Range	
		Temp. Coefficient	
Packaging Specifications		Capacitance Change with	
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC	

Specifications	
Capacitance	0.039 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	25.641 GOhms

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